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Product Specifications Approval Sheet

Product Description: TCX0	O SMD 3.2x2.5	12MHz
TST Part No.: TX0605BA5	5332	
Customer Part No.:		
Customer signature required	d	
Company:		
Division:		
Approved by :		
Date:		
Checked by:	Tom Liu	Tom
Approved by:	Kelly Huang	Kelly Huang
Date:	06/14/2022	7

- 1. Customer signed back is required before TST can proceed with sample build and receive orders.
- 2. Orders received without customer signed back will be regarded as agreement on the specifications.
- 3. Any specifications changes must be approved upon by both parties and a new revision of specifications shall be released to reflect the changes.



MODEL	NO.:	REV. NO.: 1
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TX0605BA5332

Revise:

Rev.	Rev.Page	Rev. Account	Date	Ref. No.	Reviser
1	N/A	Initial release	06/14/22'	N/A	Tom Liu



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SMD 3.2x2.5 12MHz TCXO

MODEL NO.: REV. NO: 1

TX0605BA5332

Features:

Surface Mount Seam Weld Package

- **Excellent Reliability Performance**
- Good Frequency Perturbation and Stability over temperature
- Moisture Sensitivity Level (MSL): Level-1

RoHS Compliant Lead free Lead-free soldering

Application:

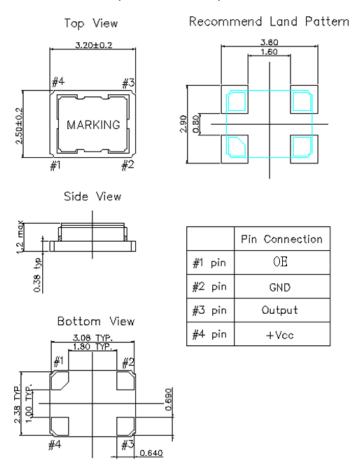
- 3.3 V Supply Voltage CMOS Output
- Option stand-by function for output.

Electrical Characteristics:

Specifications					
12.000000 MHz					
-40°C to +85°C					
-40°C to +85°C					
3.3 V +/- 5%					
15pF(AC coupled)					
CMOS					
0.2 * Vcc max 0.8 * Vcc min					
6 mA max					
40% ~ 60%					
+/- 1.5 ppm max @ 25°C +/- 3°C					
+/- 1.0 ppm max @ 25°C +/- 3°C					
+/- 2.5 ppm reference to 25°C					
+/- 0.3 ppm					
+/- 0.2 ppm					
3.0 msec max.					

Aging	+/-1.0ppm / 1 st year @25°C
Phase Noise	-130 dBc/Hz Typ. at 1kHz offset
Enable/Disable Function (OE function)	PIN 1: 0.8 * Vcc min, PIN 3:Enable PIN 1: 0~0.2 * Vcc, PIN 3:Disable PIN 1: Do not use in open condition

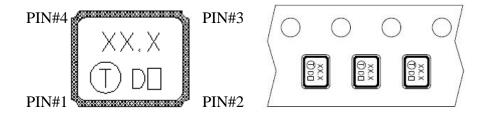
Mechanical Dimensions: (Unit: mm)



Marking:

Line 1: Frequency (12.0)

Line 2: TST Logo + Date Code + Product Code (\square is TST internal tracking code, could be a~z and A~Z)



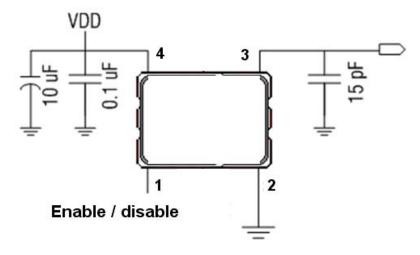
Date Code Table

WK01	WK02	WK03	WK04	WK05	WK06	WK07	WK08	WK09	WK10	WK11	WK12	WK13
Α	В	С	D	Е	F	G	Н	I	J	K	L	М
WK14	WK15	WK16	WK17	WK18	WK19	WK20	WK21	WK22	WK23	WK24	WK25	WK26
N	0	Р	Q	R	S	Т	U	V	W	Х	Υ	Z
WK27	WK28	WK29	WK30	WK31	WK32	WK33	WK34	WK35	WK36	WK37	WK38	WK39
а	b	С	d	TeAI-	SAW 7	EGHN	ОВОС	Y CO.	, LTD.	k	1	TS
WK40	WK41	WK42	WK43	WK44	WK45	WK46	WK47	WK48	WK49	WK50	WK51	WK52
n	0	q	a	r	s	t	u	V	w	х	VIX	ıcası

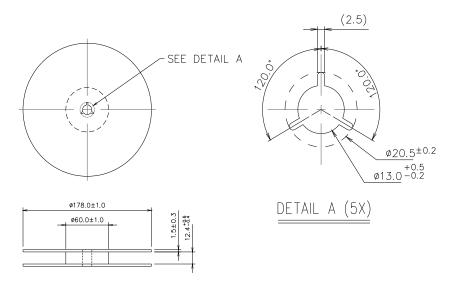
Product Code Table: (Under line With Even Year and Odd Year for Nothing)

	Product Code					
2013	2015	2017	2019	2021	2023	
2014	2016	2018	2020	2022	2024	

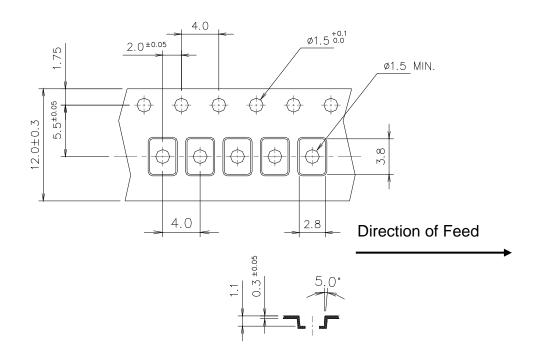
Recommended Circuit



Reel Dimensions (mm):



Tape Dimensions (mm):

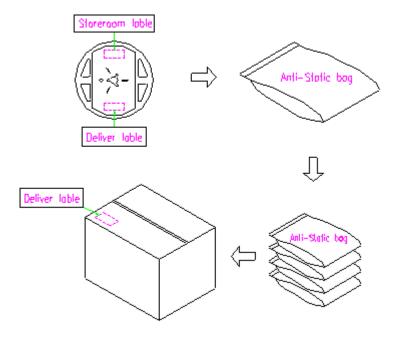


[NOTE]:

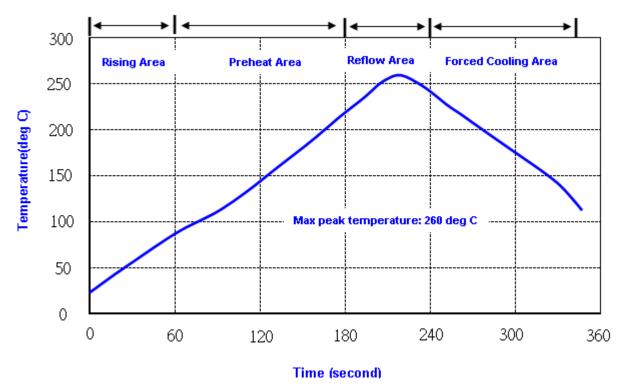
- 1. Unless otherwise specified tolerance on dimension +/-0.1 mm.
- 2. Material: conductive polystyrene with color black.
- 3. 10 pitch cumulative tolerance +/-0.2 mm.

Packing Quantity/Packing:

3K pcs maximum per reel



Reflow Profile:



Note: 1.Max peak temperature: 260+/-5 deg C; Time: 10+/-2 sec

2. Temperature: 217+/-5 deg C; Time: 90~100 sec

Notes of the Usage:

- 1. Touch the solder iron at 260+/-5 deg C onto the leads for 10+/-2 sec max or touch the solder at 350+/-5 deg C onto the leads for 3+/-0.5 sec.
- 2. In the customer's reflow process, if it will remain some mechanical stress at the soldering terminals, also make some cracks on the soldering termination. Some cracks will cause open or short circuit and cause of thermal increasing or smoking. Don't make any excess mechanical stress to soldering points.
- 3. In case of giving a heavy shock to the products, it may make an open or short circuit and cause of thermal increasing and smoking. To avoid heavy shock impact applying to products is strictly required.
- 4. Ultrasonic cleaning should be avoided to prevent damage to the TCXO.
- 5. Do Not Use Ultrasonic-Wave Soldering or Wave Solder with Package Immersed in Solder.

Notes of the Storage:

- 1. To keep products under the condition at the room temperature (-5~35 deg C) with normal humidity (45~75%). Absorption of moisture and dewdrop may make inferiority of characteristics and a short circuit.
- 2. Oxidization of terminals shall make the solderability more inferior. Dusts and corrosive gas will make a cause of the open or short circuit. Keep it in the clean place where is not in dusty and no corrosive gas.
- 3. Use the unti-static material to the storage package.
- 4. Don't put any excess weight to the TCXO in the storage process.
- 5. Don't move the product from the cold place to the hot place in the short time, otherwise it may make some dew-drop, then a short circuit may happen in case.
- 6. Storage periods should be maximum 6 months under condition of above item 1 after delivery from TST factory.
- 7. Once open the bag, there is possibility of electrical characteristics deterioration due to absorption of moisture. So, please use parts within 7 days after opening the bag.
- 8. If you have to keep parts without using after opening the bag, please put the drying agent in the bag, fold the bag and keep it in the place where temperature and humidity are controlled (nitrogen atmosphere box etc.)

Reliability Specifications

Test name	Test process / method	Reference standard						
Mechanical characteristics								
resistance to Soldering heat (IR reflow)	Temp./ Duration: 260°C /10sec x2 times Total time: 4min.(IR-reflow)	-300(301)M(II)						
Vibration	Total peak amplitude : 1.5mm Vibration frequency : 10 to 55 Hz Sweep period : 1.0 minute Vibration directions : 3 mutually perpendicular Duration : 2 hr / direc.	MIL-STD 202F method 201A						
Mechanical Shock	directions : 3 impacts per axis Acceleration : 3000g's, +20/-0 % Duration : 0.3 ms (total 18 shocks) Waveform : Half-sine	MIL-STD 202F method 213C						
Solderability	Solder Temperature:265±5°C Duration time: 5±0.5 seconds.	MIL-STD 883G method 2003						
Environmenta	d characteristics	•						
Thermal Shock	Heat cycle conditions -55 °C (30min) ←→ 125 °C (30min) * cycle time: 10 times	MIL-STD 883G method 1010.7						
Humidity test	Temperature: 70 ± 2 °C Relative humidity: 90~95% Duration: 96 hours	MIL-STD 202F method 103B						
Dry heat (Aging test)	Temperature : 125 ± 2 °C Duration : 168 hours	MIL-STD 883G method 1008.2 condition C						
PCT test	Pressure: 2.06kg/cm ² (2.03*10 ⁵ pa) Temperature : 121 ± 2 °C Relative humidity : 100% Duration : 24 hours	EIAJED-4701-3 B-123A						